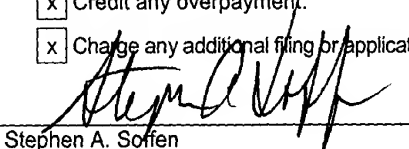




2812

AMENDMENT TRANSMITTAL LETTER				Docket No. M4065.0247/P247-A	
Application No. 09/982,953		Filing Date October 22, 2001		Examiner Jennifer M. Kennedy	
				Art Unit 2812	
Applicant(s): Allen McTeer					
Invention: USE OF ALN AS COPPER PASSIVATION LAYER AND THERMAL CONDUCTOR					
TO THE COMMISSIONER FOR PATENTS					
Transmitted herewith is an amendment in the above-identified application.					
The fee has been calculated and is transmitted as shown below.					
CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	14	- 20 =		x	0.00
Independent Claims	2	- 3 =		x	0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify):					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					0.00
<input checked="" type="checkbox"/> Large Entity <input type="checkbox"/> Small Entity					
<input checked="" type="checkbox"/> No additional fee is required for this amendment.					
<input type="checkbox"/> Please charge Deposit Account No. _____ in the amount of \$ _____ A duplicate copy of this sheet is enclosed.					
<input type="checkbox"/> A check in the amount of \$ _____ to cover the filing fee is enclosed.					
<input type="checkbox"/> Payment by credit card. Form PTO-2038 is attached.					
<input checked="" type="checkbox"/> The Commissioner is hereby authorized to charge and credit Deposit Account No. <u>04-1073</u> as described below. A duplicate copy of this sheet is enclosed.					
<input checked="" type="checkbox"/> Credit any overpayment.					
<input checked="" type="checkbox"/> Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.					
 Stephen A. Soffen Attorney Reg. No.: 31,063 DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP 2101 L Street NW Washington, DC 20037-1526 (202) 775-4742				Dated: <u>March 13, 2003</u>	

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Docket No.: M4065.0247/P247-A
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Allen McTeer

Application No.: 09/982,953

Group Art Unit: 2812

Filed: October 22, 2001

Examiner: Jennifer M. Kennedy

For: USE OF ALN AS COPPER PASSIVATION
LAYER AND THERMAL CONDUCTOR

AMENDMENT

BOX: Non-Fee Amendment
Commissioner for Patents
Washington, DC 20231

Dear Sir:

Responsive to the Office Action dated December 13, 2002, rejecting claims 22-35, Applicant amends the above-identified U.S. patent application as follows:

IN THE CLAIMS:

Rewrite claims 22 and 29 as follows:

22. A method of forming a copper interconnect structure providing electrical connection to a substrate, comprising the steps of:

forming a first contact opening into a first insulating layer of said substrate;

forming a conductive plug in said first contact opening;

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